POLYTRONICS TECHNOLOGY CORP.
24-1,Industry E.4th Rd. Science Park, Hsinchu,
Taiwan, R.O.C.
TEL: +886-3-5643931 FAX: +886-3-5644624

EVERFUSE™
Polymeric PTC Fuse

Device Specification(preliminary)

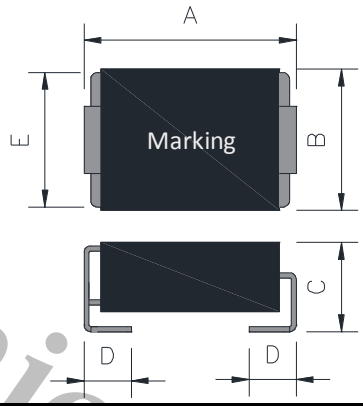
Electrical Rating

Voltage: 30V
Current: 30A

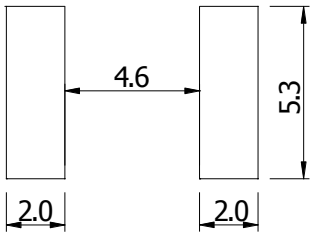
Marking :

P(Polytronics / Polystar Logo)

Figure



Recommended Pad Layout (mm)



Physical Dimensions (mm)

Part Number	A		B		C		D		E	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
SHV2920P500/30-AA	6.70	8.60	5.00	5.70	2.00	3.20	1.00	2.30	4.90	5.30

Electrical Characteristics

Part Number	I_{hold} (A)	I_{trip} (A)	V_{max} (V)	I_{max} (A)	$P_{d\ typ}$ (W)	Maximum Time-to-Trip		Resistance (Ω)	
						(A)	(Sec)	R_{min}	R_{1max}
SHV2920P500/30-AA	5.0	12.5	30	30	3.5	25.0	10.0	0.003	0.020

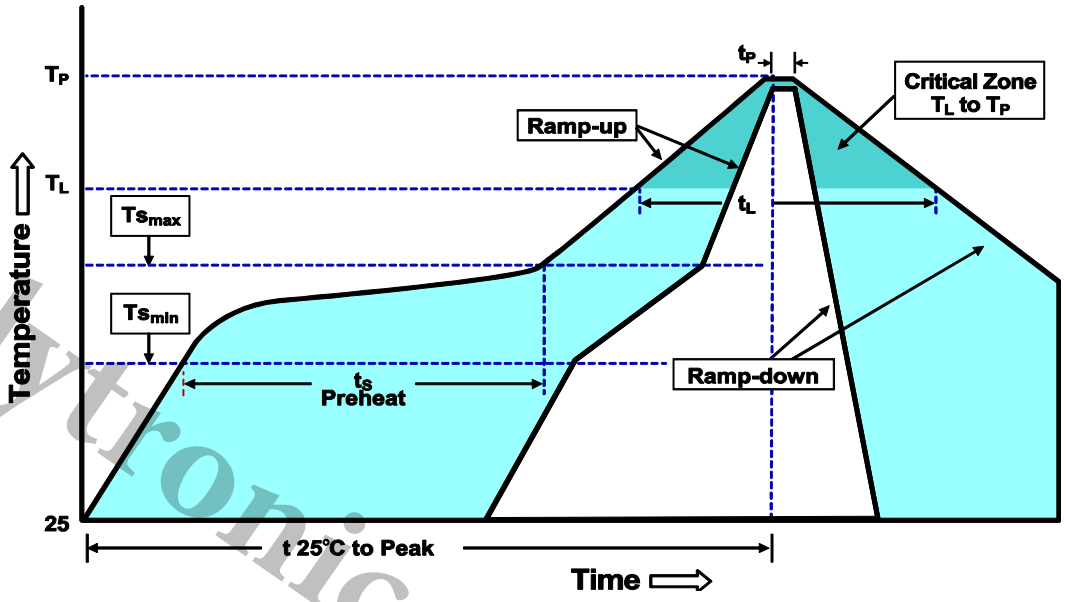
Note: I_{hold} = Hold current: maximum current device will pass without tripping in 25℃ still air.
I_{trip} = Trip Current: minimum current at which the device will trip in 25℃ still air.
Vmax = Maximum voltage device can withstand without damage at rated current (Imax)
Imax = Maximum fault current device can withstand without damage at rated voltage (Vmax)
Pd = Power dissipated from device when in the tripped state at 25℃ still air.
Rmin = Minimum resistance of device in initial (un-soldered) state.
R1max = Maximum resistance of device reflow soldering of 260℃ for 20 sec.
***Value specified were determined using the PWB with 0.150" *1.5oz copper traces.**

Caution :Operation beyond the specified rating may result in damage and possible arcing and flame.

◎ Specifications are subject to change without notice.

POLYTRONICS TECHNOLOGY CORP.
24-1,Industry E.4th Rd. Science Park, Hsinchu,
Taiwan, R.O.C.
TEL: +886-3-5643931 FAX: +886-3-5644624

Soldering Parameters



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Ts_{max} to T_P)	3℃/second max.
Preheat -Temperature Min (Ts_{min}) -Temperature Max (Ts_{max}) -Time (Ts_{min} to Ts_{max})	 150℃ 200℃ 60-180 seconds
Time maintained above: -Temperature (T_L) -Time (t_L)	 217℃ 60-150 seconds
Peak Temperature (T_P)	260℃
Time within 5℃ of actual Peak Temperature (t_P)	20-40 seconds
Ramp-Down Rate	6 ℃ /second max.
Time 25℃ to Peak Temperature	8 minutes max.
Storage Condition	0℃ ~35℃, ≦70%RH

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N_2 environment for lead-free
- Recommended maximum paste thickness is 0.25mm (0.010 inch)
- Devices can be cleaned using standard industry methods and solvents.

Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Resettable Fuses - PPTC ***category:***

Click to view products by Polytronics ***manufacturer:***

Other Similar products are found below :

0001.1010.G D38999/20WG39JN F02B250V1-4AS 9728214S-2(621) RF0627-000 RF2534-000 ASMD185-2 EN2997S61212AN EN2997SE61203AN BK-ABC-V-5-R LR4-550RAF SMD125-2 F60C500V20AS RF0078-000 RF1548-000 RF1973-000 RF2171-000 RF2531-000 RF2533-000 RF2550-000 TR600-150Q-B-0.5-0.130 BK-AGX-20 5E4795/04-1502 EN2997S61212MN EN2997SE61203MN EN2997SE61212AN EN2997SE61212MN BK1/S505-1.25-R TR-3216FF20-R TRF250-080T-B-1.0-0.125 JT06RT1832BN014 S-3-2-10 SMD100-2 FRN-R-5-6-10 FRS-R-3-2-10 LP-CC-2-1-2 LPS-RK-3-2-10SP BK-AGC-1-8-R BK-AGC-2-10-R BK-AGC-7-1-2 BK-GDC-500MA BK-MDL-1-6-10-R BK-SFE-4 BK-ABC-1-R BK-C518-250-R BK-GDB-2A BK-MDL-1-8-R BK-MDL-6 BK-AGC-5-R BK-ATC-2